

JIS

JAPANESE INDUSTRIAL STANDARD

Testing methods for creep rupture of adhesive bonds

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JAPANESE INDUSTRIAL STANDARD

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Testing methods for creep rupture of
adhesive bonds

K 6859-1994

1. Scope This Japanese Industrial Standard specifies the testing methods for creep rupture characteristics of adhesive bonds shown when a bonded test piece is statically loaded for long duration at specified temperature.

Remarks: The standards cited in this Standard are listed in the following.

JIS K 6800 Glossary of terms used in adhesives and adhesion

JIS K 6848 General rules for testing methods of bonding strength of adhesives

JIS K 6849 Testing methods for tensile strength of adhesive bonds

JIS K 6850 Testing methods for shear strength of adhesive bonds by tensile loading

JIS K 6851 Testing methods for tensile shear strength of wood-to-wood adhesive bonds

JIS K 6900 Plastics - Vocabulary [ISO 472:1988]

JIS Z 8703 Standard atmospheric conditions for testing

2. Definitions The definitions of main terms used in this Standard shall follow those specified in JIS K 6800 and JIS K 6900.

3. General condition for tests

3.1 Standard atmospheric condition in laboratory The standard atmospheric condition in laboratory shall follow 3.1 of JIS K 6848.

In case of wood and wooden material, class 5 temperature ($20 \pm 5^{\circ}\text{C}$) of standard atmospheric condition and class 20 humidity [$(65 \pm 20) \%$] of standard atmospheric condition specified in JIS Z 8703 may be adopted. In this case, the temperature and humidity in the laboratory adopted for test shall be recorded in the test results.

3.2 Conditioning of adhesives bonds and rounding off of measured values The conditioning of adhesives bonds and rounding off of measured values shall follow respectively 3.2 and 3.3 of JIS K 6848.

4. Sampling method and handling method of adhesive bonds The sampling method and handling method of adhesive bonds shall follow 4. of JIS K 6848.